

Low Capacitance TVS Diode Array

APPLICATIONS

- ◆ Ethernet - 10/100/1000 Base T
- ◆ Cellular Phones
- ◆ I²C Bus Protection
- ◆ Parallel & Serial Port Protection
- ◆ Personal Digital Assistant (PDA)
- ◆ Microcontroller Input Protection
- ◆ ISDN S/T Interface
- ◆ WAN/LAN Equipment

IEC COMPATIBILITY

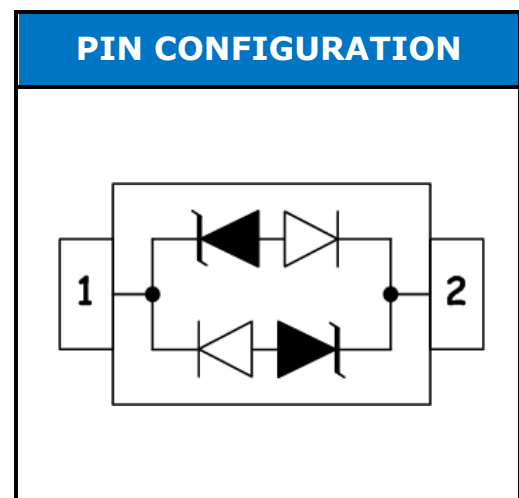
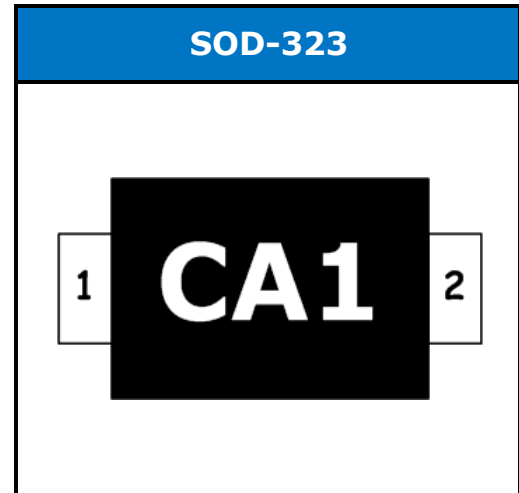
- ◆ IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- ◆ IEC61000-4-4 (EFT) 40A (5/50 η s)

FEATURES

- ◆ 200 Watts Peak Pulse Power per Line (tp=8/20μs)
- ◆ Protects One Bidirectional I/O line
- ◆ Low clamping voltage
- ◆ Working voltages : 2.5 and 3.3V
- ◆ Low leakage current

MECHANICAL CHARACTERISTICS

- ◆ JEDEC SOD-323 Package
- ◆ Molding Compound Flammability Rating : UL 94V-0
- ◆ Weight 5.0 Milligrams (Approximate)
- ◆ Quantity Per Reel : 3,000pcs
- ◆ Reel Size : 7 inch
- ◆ Lead Finish : Lead Free



DEVICE CHARACTERISTICS

MAXIMUM RATINGS (@ 25°C Unless Otherwise Specified)			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp=8/20μs waveform)	P _{PP}	200	Watts
Lead Soldering Temperature	T _L	260 (10 sec.)	°C
Operating Temperature Range	T _J	-55 ~ 150	°C
Storage Temperature Range	T _{STG}	-55 ~ 150	°C

ELECTRICAL CHARACTERISTICS PER LINE (@ 25°C Unless Otherwise Specified)									
PART NUMBER	DEVICE MARKING	V _{RWM}	V _B	I _T	V _C	V _C		I _R	C _T
		(V) (max.)	(V) (min.)	(mA)	@1A (max.)	(max.)	(@A)	(μA) (max.)	(pF) (typ.)
TUSD02FBX	CA2	2.5	3.0	1	4.8	15.0	15	1	0.6
TUSD03FBX	CA1	3.3	3.5	1	5.8	15.0	10	1	0.6

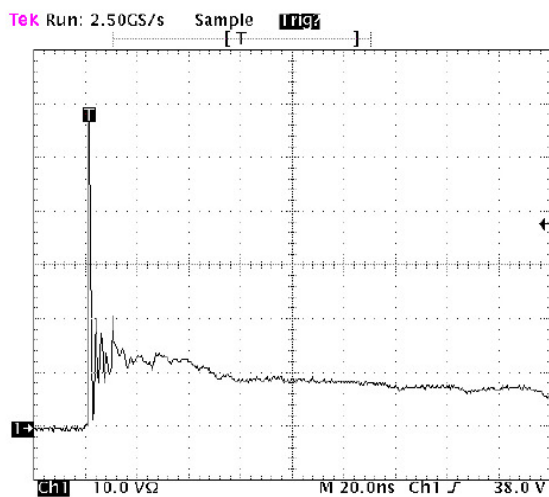


Figure 1. ESD Clamping Voltage Screenshot Positive 8 kV contact per IEC 61000-4-2

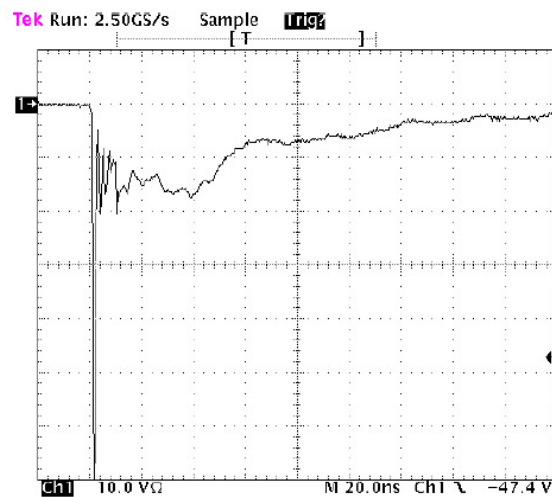
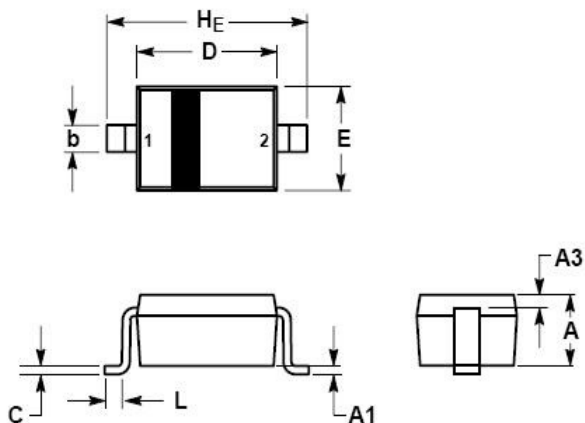


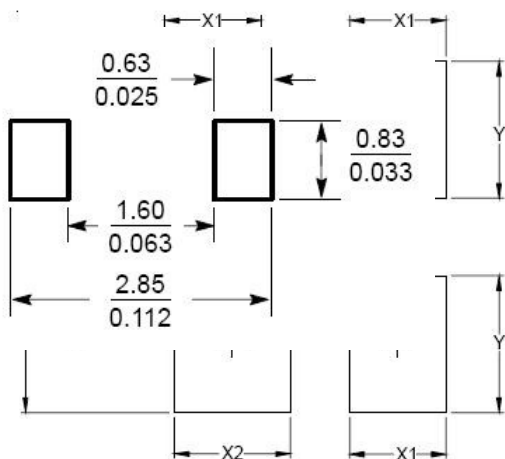
Figure 2. ESD Clamping Voltage Screenshot Negative 8 kV contact per IEC 61000-4-2

SOD-323 PACKAGE OUTLINE & DIMENSIONS



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105

*** SOLDERING FOOTPRINT**



DIMENSIONS		
DIM	INCHES	MILLIMETERS
C	(.087)	(2.20)
E1	.076	1.92
E2	.068	1.72
G	.031	0.80
X1	.039	1.00
X2	.047	1.20
Y	.055	1.40
Z	.141	3.60